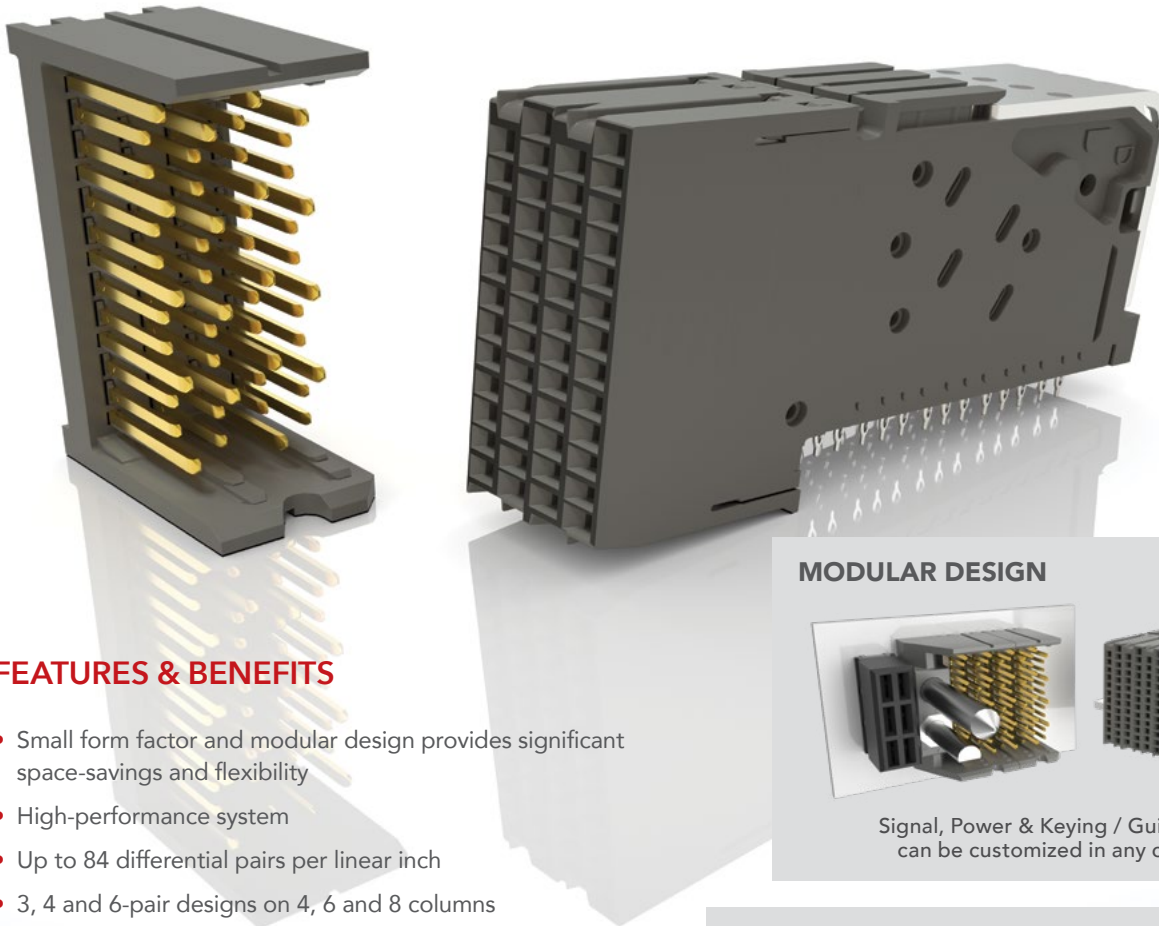


HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

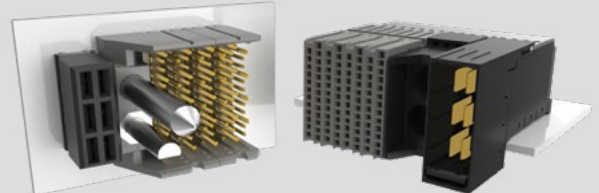
16
Gbps



FEATURES & BENEFITS

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and side walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane. Visit samtec.com?BSP or contact HSBP@samtec.com
- Press-fit extraction and insertion tool options; please visit samtec.com/tooling for details

MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR



XCede[®] HD
Up to 84 pairs per linear inch



Traditional Backplane
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

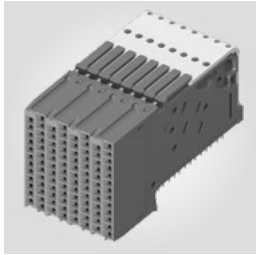
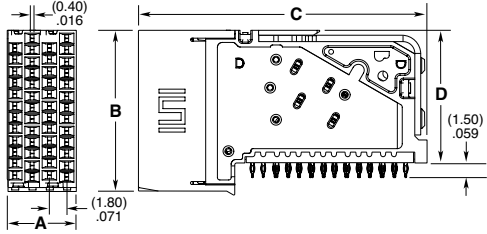
KEY SPECIFICATIONS

| SERIES | INSULATOR MATERIAL | CONTACT MATERIAL | PLATING | OPERATING TEMP RANGE | CURRENT RATING | VOLTAGE RATING |
|-----------|--------------------|---|-------------------------------------|----------------------|-------------------|----------------|
| HDTM/HDTF | LCP | Phosphor Bronze (HDTM) Copper Alloy (HDTF) | Au or Sn over 50 μ" (1.27 μm) Ni | -40 °C to + 105 °C | 1.5 A per contact | 48 VAC |
| HPTS/HPTT | LCP | Copper Alloy | Au or Sn over 50 μ" (1.27 μm) Ni | -40 °C to + 105 °C | 10 A per blade | 48 VAC |

(1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE RECEPTACLE

| HDTF | PAIRS PER COLUMN | NO. OF COLUMNS | PLATING | RA | WAFERS | IMPEDANCE |
|------|------------------|----------------|---|----|--|---------------------------------------|
| | -3, -4, -6 | -04, -06, -08 | -S = 30 μ" (0.76 μm) Gold on Contact Area, Matte Tin on Tail | | -LC = Standard -HS = High-Speed | -100 = 100 Ω -085 = 85 Ω |

HDTF Board Mates:
HDTM

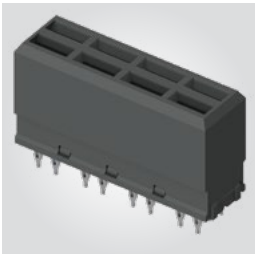
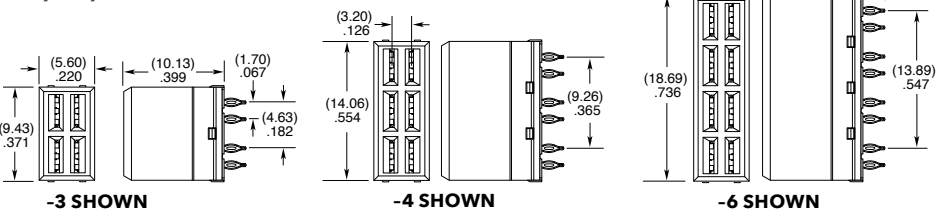
| NO. OF COLUMNS | A | PAIRS PER COLUMN | B | C | D |
|----------------|----------------|------------------|----------------|----------------|----------------|
| -04 | (7.2) .283 | -3 | (12.8) .504 | (26.0) 1.02 | (9.9) .390 |
| -06 | (10.8) .425 | -4 | (16.4) .646 | (29.4) 1.16 | (13.5) .531 |
| -08 | (14.4) .567 | -6 | (23.6) .929 | (36.6) 1.44 | (20.7) .815 |

View complete specifications at: samtec.com?HDTF

(3.20 mm) .126" PITCH • POWER MODULES

| HPTS | BODY HEIGHT | PLATING | D | ORIENTATION |
|----------|--|---|---|-------------------|
| = Socket | Based on Pair Count of Signal Modules (HDTM) | -S = Standard Gold on Contact Area, Matte Tin on Tail | | -VT = Vertical |


HPTS Mates with:
HPTT, BSP

View complete specifications at: samtec.com?HPTS

| HPTT | BODY HEIGHT | PLATING | POSITION NO. 1 | POSITION NO. 2 | POSITION NO. 3 | POSITION NO. 4 | D | ORIENTATION |
|------------|---|---|--|--|--|--|---|----------------------|
| = Terminal | Based on Pair Count of Signal Modules (HDTF, BSP) | -S = Standard Gold on Contact Area, Matte Tin on Tail | Contact Wipe Column A & B | Contact Wipe Column A & B | Contact Wipe Column A & B (-4 & -6 Height Only) | Contact Wipe Column A & B (-6 Height Only) | | -RA = Right-angle |
| | -3, -4, -6 | | -3 = (4.5 mm) 0.18" -6 = (5.5 mm) 0.22" | -3 = (4.5 mm) 0.18" -6 = (5.5 mm) 0.22" | -3 = (4.5 mm) 0.18" -6 = (5.5 mm) 0.22" | -3 = (4.5 mm) 0.18" -6 = (5.5 mm) 0.22" | | |

HPTT Mates With:
HPTS



Notes:
Some lengths, styles and options are non-standard, non-returnable. XCede® is a registered trademark of Amphenol.

View complete specifications at: samtec.com?HPTT

